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2323
2323-HV

BRAZING CONDUCTOR

ESL 2323 is a 72% Ag / 28% Cu fluxless and fritless eutectic brazing alloy available in paste form suitable for screen printing. Typical uses are for joining metal parts to moly-manganese or nickel metallized ceramic, package fabrication, and making high temperature connections where the joint will see temperatures greater than the melting point of soft solders. The metal parts should be nickel plated for best results. ESL 2323-HV is a higher viscosity version of 2323 and is designed to provide better printing definition.

PASTE DATA

RHEOLOGY:		Thixotropic, screen printable paste
VISCOSITY: (Brookfield RVT, ABZ Spindle, 10 rpm, 25.5°C±0.5°C)	**2323**	65±5 Pa·s
	2323-HV	80±5 Pa·s
SOLIDS:	**2323**	93±1%
	2323-HV	94±1%
SHELF LIFE:(25°C)		6 months

PROCESSING

SCREEN MESH/EMULSION:	200-325/25 µm
LEVELING TIME: (25°C)	5-10 minutes
DRYING AT 125°C:	10-15 minutes
FIRING RANGE:	810°C spike, 10-20 seconds
BRAZING ATMOSPHERE:	Wet hydrogen, forming gas, cracked ammonia

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See Caution and Disclaimer on other side.

MELTING POINT: (Eutectic) 779°C

COMPATIBILITY: Can be brazed to moly-manganese or hydrogen-fired thick film nickel (e.g., ESL 2505-H2). Not compatible with most air firing thick film metallization, since this process will cause lower adhesion of the metallization when exposed to reducing atmospheres at high temperatures.